



Wafer Fab Capability



Wafer Loading: Automated wafer loading throughout the Fab prevents handling-induced mechanical damage.



Ion Implant: State-of-the-art high current implanter capable of the full range of dose requirements.



Wafer Cleaning: Semi-automated wafer cleaning at all diffusion operations using state-of-the-art chemistry resulting in low particulate and metallic levels.



Diffusion: Automated diffusion tubes with cantilever load, computerized control and recipe management, and external torch assemblies.



Wafer Fab Capability

Location: Worcester, Massachusetts

Wafer Size: 150mm (6")

Registration: ISO9000 & QS9000 Certified

Clean Room Quality: Class 100

Process Technologies:

Bipolar: 30 & 50 Volt

BiCMOS: 60 Volt

BCD: 60 Volt

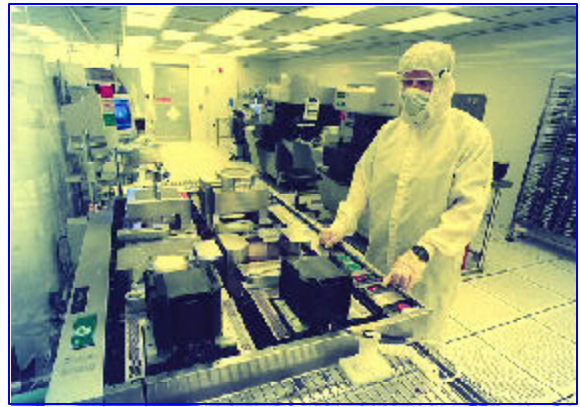
Products Manufactured:

Motor Drivers & Controllers

Power Interface ICs

Power Management ICs

Hall-Effect Sensors



Photolithography: 1 X Stepper based with 1.25 μm capability, operating in a class 100 clean room with ULPA filters. Operating conditions <10 particles per cubic foot.



Wet Etching: Semi-automated with programmed robotic processing, with recirculated and filtered chemicals.



Plasma Etching: Automated equipment with end-point detection and robotic wafer handling.